

Peichun Hua

Computer Science and Engineering, School of Data Science
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EDUCATION

The Chinese University of Hong Kong , Shenzhen B.Eng in Computer Science Engineering Overall GPA: 3.94/4.00 — Major GPA: 4.00/4.00 — Rank: 1.5% (5/326)	September 2022 — June 2026
University of North Carolina , Chapel Hill Overall GPA: 4.00/4.00 Exchange Student	September 2024 - May 2025 Computer Science Department

PUBLICATION

Peichun Hua, Hanxiu Zhang, Tuo Li, and Yue Zheng. “Securing On-device Transformer with Hardware Binding and Reversible Obfuscation.” **Accepted** by *The 41st Annual Computer Security Applications Conference (ACSAC) 2025* (CORE: A, CCF-B, TH-CPL: B, Acceptance Rate = $84/446 \approx 18.8\%$, [Code], [Paper]; Awarded “Artifact Available,” “Artifact Reviewed,” and “Artifact Reproducible” badges from IEEE).

Peichun Hua, Hao Li, Shanghao Shi, Zhiyuan Yu, and Ning Zhang. “Rethinking Jailbreak Detection of Large Vision Language Models with Representational Contrastive Scoring.” *Submitted*, ACL Rolling Review. *ARR scores: OA=3.75, Meta=4.0 (Recommended for ACL 2026 main)*. [Code], [Paper (arXiv)]

Peichun Hua, Hanxiu Zhang, Tuo Li, Yue Zheng, and Wenye Liu. “Live Demonstration: Hardware-Bound IP Protection for Edge-deployed Transformers.” **Accepted** by *IEEE International Symposium on Circuits and Systems (ISCAS) 2026* (CCF-C, TH-CPL: B)

Xin Wang, **Peichun Hua**, Wenye Liu, and Yue Zheng. “Error-Correction-Free PUF Authentication via Scalable Open-Set Classification.” *Under Review*, *ACM/IEEE The 63rd Chips to Systems Conference (DAC) 2026*

AWARDS

Academic Honors

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| • Dean’s List, School of Data Science, CUHK-Shenzhen | 2022–2023, 2023–2024 |
| • Academic Performance Scholarship (Class B, Top <2%), School of Data Science | 2023–2024 |
| • Academic Performance Scholarship (Class C, Top <5%), School of Data Science | 2022–2023 |
| • University Research Award (with scholarship) | 2024 Fall, 2025 Spring |

Research Awards

- *Student Conferenceship*, 41st Annual Computer Security Applications Conference (ACSAC 2025) [ACSAC Website]
- *Artifact Available*, *Artifact Reviewed*, and *Artifact Reproducible* Badges — IEEE, for paper “Securing On-device Transformer with Hardware Binding and Reversible Obfuscation” at ACSAC 2025
- Fully Funded International Research Internship — McKelvey School of Engineering, Washington University in St. Louis
Summer 2025

EXPERIENCE

School of Data Science, CUHK-Shenzhen <i>Undergraduate Research Intern</i>	Shenzhen, China September 2024 – present
• Advisor: Prof. Yunming Xiao	
McKelvey School of Engineering, Washington University in St. Louis <i>Summer Research Intern</i>	Missouri, USA May 2025 – August 2025
• Fully funded by International Student Research Internship Program	
• Advisor: Prof. Ning Zhang	
School of Science and Engineering, CUHK-Shenzhen <i>Undergraduate Research Intern</i>	Shenzhen, China May 2024 – May 2025
• Advisor: Prof. Yue Zheng	

SKILLS

- **Coursework:** Achieved *A* grade in all listed *graduate-level* coursework
Cryptography 3D Computer Vision Hardware Security and Side-Channels
Efficient Deep Learning Research Topics in Computer Security Formal Methods in Computer Security
- **Language Proficiency:** TOEFL 108 (R29+L29+S23+W27), GRE 328(V161+Q167+3.5)